

Special Issue

Non-Destructive Characterization and Processing of Composite Materials

Message from the Guest Editor

This Special Issue aims to provide a good forum for scientists and engineers to share and discuss their pioneering original findings or insightful reviews on the characterization of composite materials. Reports on *non-destructive* characterization research towards process enhancement and the development/application of an advanced characterization method are particularly welcome. The proper characterization of heterogeneous composite materials is still a challenging task, since the majority of characterization methods often require the size reduction and dissolution of a material that average the whole material and could overlook potential issues associated with spatially heterogeneous materials and values associated with fine grains.

Guest Editor

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Deadline for manuscript submissions

closed (30 November 2021)



Journal of Composites Science

an Open Access Journal
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Impact Factor 4.6
CiteScore 6.7



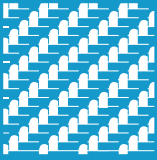
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